Preferred Device

# NPN Silicon General Purpose High Voltage Transistors

This NPN Silicon Planar Transistor is designed for general purpose amplifier applications. This device is housed in the SC-70/SOT-323 and SC-59 packages which are designed for low power surface mount applications.

#### **Features**

• Pb-Free Package is Available

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit
Collector-Base Voltage	V <sub>(BR)CBO</sub>	300	Vdc
Collector-Emitter Voltage	V <sub>(BR)CEO</sub>	300	Vdc
Emitter-Base Voltage	V <sub>(BR)EBO</sub>	6.0	Vdc
Collector Current – Continuous	Ic	150	mAdc

#### THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	150	mW
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>stg</sub>	-55~+150	°C

#### **ELECTRICAL CHARACTERISTICS**

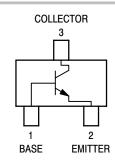
Characteristic	Symbol	Min	Max	Unit
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	300	-	Vdc
Collector-Base Breakdown Voltage $(I_C = 100 \mu Adc, I_E = 0)$	V <sub>(BR)CBO</sub>	300	-	Vdc
Emitter-Base Breakdown Voltage $(I_E = 100 \mu Adc, I_E = 0)$	V <sub>(BR)EBO</sub>	6.0	-	Vdc
Collector-Base Cutoff Current (V <sub>CB</sub> = 200 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	-	0.1	μΑ
Emitter–Base Cutoff Current $(V_{EB} = 6.0 \text{ Vdc}, I_B = 0)$	I <sub>EBO</sub>	_	0.1	μΑ
DC Current Gain (Note 2) ( $V_{CE} = 10 \text{ Vdc}$ , $I_{C} = 1.0 \text{ mAdc}$ ) ( $V_{CE} = 10 \text{ Vdc}$ , $I_{C} = 30 \text{ mAdc}$ )	h <sub>FE1</sub> h <sub>FE2</sub>	25 40	- 1	1
Collector-Emitter Saturation Voltage (Note 2) (I <sub>C</sub> = 20 mAdc, I <sub>B</sub> = 2.0 mAdc)	V <sub>CE(sat)</sub>	ı	0.5	Vdc

- 1. Device mounted on a FR-4 glass epoxy printed circuit board using the minimum recommended footprint.
- 2. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, D.C.  $\leq$  2%.



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SC-70 (SOT-323) CASE 419 (SCALE 2:1) SC-59 CASE 318D (SCALE 2:1)

### **MARKING DIAGRAMS**





1D = Device Marking CodeM = Date Code

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MSD42WT1	SC-70/SOT-323	3000/Tape & Reel
MSD42WT1G	SC-70/SOT-323	3000/Tape & Reel
MSD42T1	SC-59	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

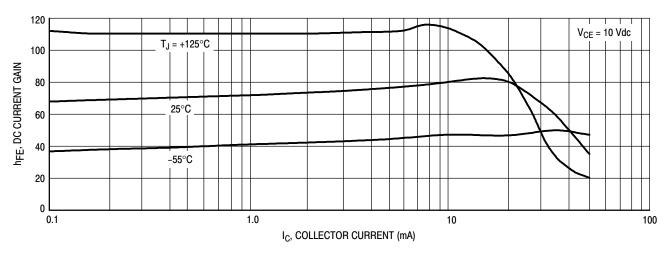


Figure 1. DC Current Gain

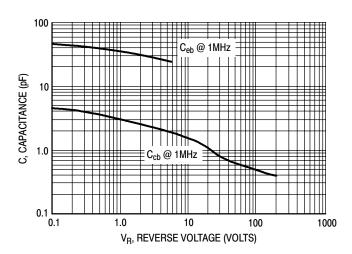
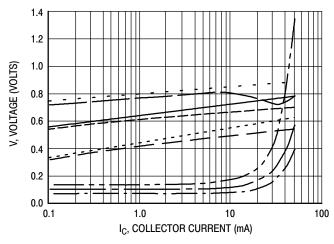
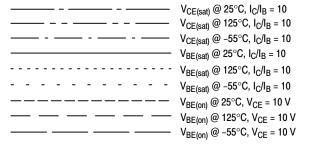


Figure 2. Capacitance

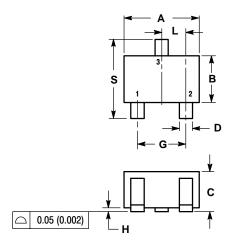


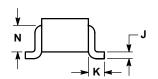




### **PACKAGE DIMENSIONS**

#### SC-70 (SOT-323) CASE 419-04 ISSUE L



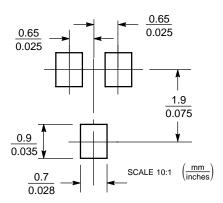


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
C	0.032	0.040	0.80	1.00
D	0.012	0.016	0.30	0.40
G	0.047	0.055	1.20	1.40
Н	0.000	0.004	0.00	0.10
J	0.004	0.010	0.10	0.25
K	0.017 REF		0.425 REF	
L	0.026 BSC		0.650 BSC	
N	0.028 REF		0.700 REF	
S	0.079	0.095	2.00	2.40

STYLE 3: PIN 1. BASE 2. EMITTER 3. COLLECTOR

#### **SOLDERING FOOTPRINT\***

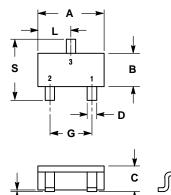


SC-70/SOT-323

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

SC-59 CASE 318D-04 ISSUE F

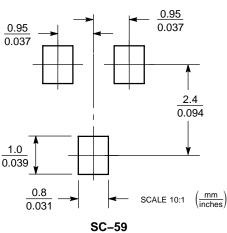


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   V14 5M 1982
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		TERS INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.70	3.10	0.1063	0.1220
В	1.30	1.70	0.0512	0.0669
С	1.00	1.30	0.0394	0.0511
D	0.35	0.50	0.0138	0.0196
G	1.70	2.10	0.0670	0.0826
Н	0.013	0.100	0.0005	0.0040
J	0.09	0.18	0.0034	0.0070
K	0.20	0.60	0.0079	0.0236
L	1.25	1.65	0.0493	0.0649
S	2.50	3.00	0.0985	0.1181

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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